

**SPECIFICATION AMENDMENTS:**

Please amend the specification as follows:

Please replace the paragraph on page 1, lines 7 through 13, with the following amended paragraph:

--In recent years, there has been a demand for higher density integration and size reduction of a semiconductor device. To this end, a multichip module (MCM, see Japanese Unexamined Patent Publication No. 2000-270721 2000-188369) and a chip scale package (CSP, see Japanese Unexamined Patent Publication No. 2002-118224) have been developed which satisfy the aforesaid demand.--